

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

**Title of
Invention**METHOD FOR MANUFACTURING WAFER LEVEL CHIP SCALE PACKAGE
STRUCTURE

Application Number :

Date :

First Named Applicant: Mr. Min-Chih Hsuan

Attorney Docket Number: 13301-US-PA

TOTAL FEE AUTHORIZED \$ 810

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Utility Filing Fee	1001	770	770
Subtotal For Basic Filing Fees: \$ 770			

EXTRA CLAIM FEES

Fee Description	Extra Claim	Fee Code	Amount \$	Fee Paid \$
Total Claims : 19	0	1202	18	0
Independent Claims : 2	0	1201	86	0
Subtotal For Extra Claims Fees: \$ 0				

ASSIGNMENT FEES

Fee Description	Property Number	Quantity	Fee Code	Amount \$	Fee Paid \$
Recording Each Patent Assignment Per Property Fee	00000000	1	8021	40	40
Subtotal For Additional Fees: \$40					

AUTHORIZED BILLING INFORMATION**The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Credit account number: 1007
Expiration Date (YYYYMMDD): 2005-12-31
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